A NOVEL TWO-PORT 6T CMOS SRAM CELL STRUCTURE FOR LOW-VOLTAGE VLSI SRAM WITH SINGLE-BIT-LINE SIMULTANEOUS READ-AND-WRITE ACCESS (SBLSRWA) CAPABILITY

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Abstract

This paper reports a two-port 6T CMOS SRAM cell structure for low-voltage VLSI SRAM with single-bit-line simultaneous read-and-write access (SBLSRWA) capability. With a unique structure by connecting the source terminal of an NMOS device in the SRAM cell to the write word line, this SRAM cell can be used to provide SBLSRWA capability for 1V two-port VLSI SRAM as verified by SPICE results.

Summary

Introduction

In a conventional SRAM cell as shown in Fig. 1, double bit lines have been used for read and write accesses — read and write operations are done via the same pair of bit lines. Therefore, while designing two-port memory IC with simultaneous read and write capability, two more pass transistors and an extra pair of bit lines are needed to be incorporated into the memory cell. As a result, the size of the memory cell is increased substantially. If the memory cell structure can be simplified to provide the operation with only one bit line for read and the other bit line for write, the size of this memory cell can be reduced a lot for implementing two- port VLSI SRAM.

The difficulty of using the conventional SRAM cell with single-bit-line write access can be perceived from Fig. 2. As shown in Fig. 2, if logic-1 is to be written from the left bit line WBL via the pass transistor M_{N1} into the left side of the memory cell (node n1), where logic-0 is originally stored. During the write-in operation, the voltage at node n1 cannot be raised to exceed $V_{dd} - V_{TN}$ by the write bit line WBL, where V_{dd} is the power supply voltage and V_{TN} is the threshold voltage of the pass transistor M_{N1} . In addition, since the ratioed-logic structure, which is made of the NMOS devices M_{P3} , which is the driver of the bit line WBL, plus the fact that the electron mobility of the NMOS devices







Figure 2. Single-bit-line write-1 operation of the conventional 6T SRAM cell.

is larger than the hole mobility of the PMOS device, the

This work is supported under R.O.C. National Science Council Contracts #88-2215-E002-033 & #88-2622-E002-028.

voltage of node n1 is difficult to be raised during the singlebit-line write-logic-1 operation. As a result, the conventional SRAM cell structure cannot be used for two-port memory circuits with the single-bit-line write-logic-1 operation.

Although several techniques [1]-[2] have been applied to resolve this difficulty, the penalty cannot be justified for realizing two-port VLSI SRAM. Using DTMOS techniques, a two-port 6T SOI CMOS SRAM cell for low-voltage SRAM with SBLSRWA has been reported [3]. In this paper, with a unique structure by connecting the source terminal of an NMOS device in the SRAM cell to the write word line, this 6T SRAM cell can be used to provide single-bit-line simultaneous read-and-write access capability for 1V twoport VLSI SRAM.

SBLSRWA SRAM Cell

Fig. 3 shows the single-bit-line simultaneous read-and-write access (SBLSRWA) two-port 6T SRAM cell. As shown in the figure, the source terminal of the NMOS device M_{N3} is connected to the write word line WWL instead of to the ground as in the conventional SRAM cell. In the SBLSRWA memory cell, the left side is connected to the write bit line WBL via the pass transistor M_{N1} , which is controlled by write word line WWL. The right side of the SBLSRWA memory cell is connected to the read bit line RBL via the pass transistor M_{N2} , which is controlled by the read word line RWL. By this configuration, simultaneous read and write accesses of the SBLSRWA can be facilitated. During the write-logic-1 access, initially, logic-0 is stored at node n1. The previous problem associated with the turn-on of the



Figure 3. Structure of the two-port simultaneous read-andwrite access (SBLSRWA) 6T SRAM cell.

NMOS device M_{N3} in the conventional SRAM cell for single-bit-line write-logic-1 access can be avoided. Instead, owing to the write word line WWL-connected source terminal of M_{N3} , during the single-bit-line write-logic-1 operation, the source of the NMOS device M_{N3} is tied to high, usually at V_{dd} . As a result, during the single-bit-line writelogic-1 operation, the voltage of node n1 can reach high at $V_{dd} - V_{TN}$ easily. Consequently, M_{N4} turns on and M_{P2} turns off. Thus, the right side of the SBLSRWA cell, node n2, switches to 0V, which makes the voltage of node n1 raised to 1V. This concludes the write-logic-1 operation.

In order to verify the effectiveness of the SBLSRWA SRAM cell, transient analysis during simultaneous read and write accesses of the SBLSRWA SRAM cell at a low supply voltage has been carried out. In the SBLSRWA SRAM cell under study, all six transistors have an aspect ratio of 0.3µm/0.25µm. Two parasitic capacitors of 0.1pF are assumed at write and read bit lines (WBL, RBL). Based on a 0.25µm CMOS technology, Fig. 4 shows the transient waveforms during the write access of the SBLSRWA 6T SRAM cell at V_{dd} of 1V based on SPICE simulation results. As shown in the figure, there are four cases for the write access — (1) logic-0 is written into the storage node n1, which is stored with logic-0 (logic-0 \rightarrow logic-0), (2) logic-1 is written into the storage node n1, which is stored with logic-0 (logic-0 \rightarrow logic-1), (3) logic-1 is written into the storage node n1, which is stored with logic-1 (logic-1 \rightarrow logic-1), (4)logic-0 is written into the storage node n1, which is stored with logic-1 (logic-1 \rightarrow logic-0). The transients associated with these four cases are described below.



Figure. 4 Transients during the write access of the two-port SBLSRWA 6T SRAM cell at V_{dd} of 1V.

Logic-0 \rightarrow Logic-0 Write

In this case, before the single-bit-line write-logic-0 operation

is executed (WWL=0), the storage node n1 is at logic-0 (0V) since M_{N3} is on. The write bit line WBL is also at logic-0 (0V). When WWL switches from low to high, write access is initiated. During the initial ramp-up period of WWL with its voltage before reaching the threshold voltage of M_{N1} (V_{TN}), node n1 is being charged with its voltage rising with WWL since M_{N3} is on. Note that at this time M_{N1} is off. During the ramp-up period of WWL with a voltage greater than the threshold voltage of M_{N1} (V_{TN}), M_{N1} turns on. At this time, since the write bit line is at logic-0, node n1 is discharged as shown. Due to the ratioed-logic structure of M_{N1} and M_{N3} , the voltage of node n1 is maintained at 0.15V during most of the write-logic-0 access period when WWL is at its logic-1 value (1V). After the write-logic-0 access is over, WWL ramps down. During the initial ramp-down of WWL, the transconductance of M_{N1} becomes smaller. As a result, despite the down-slew of WWL, due to the ratioed-logic structure of M_{N1} and M_{N3} , the voltage of node n1 slews upward during the initial ramp-down of WWL. When WWL is below V_{1N} , M_{N1} turns off and the voltage of node n1 slews downward with the ramp-down of WWL. When WWL comes down to the logic-0 level (0V), node n1 is also pulled down to 0V. This accomplishes the logic-0 \rightarrow logic-0 write operation.

Logic-0 \rightarrow Logic-1 Write

In this case, before the single-bit-line write-logic-1 operation is executed (WWL=0), the storage node n1 is at logic-0 (0V) since M_{N3} is on. The write bit line WBL is at logic-1 (1V). During the initial ramp-up period of WWL when WWL is smaller than V_{TN} , as in the logic-0 \rightarrow logic-0 case, node n1 is being charged with its voltage rising with WWL since M_{N3} is on. When WWL is greater than V_{TN} , M_{N1} turns on. Different from the situation in the logic-0 \rightarrow logic-0 case, node n1 rises further since WBL is now at 1V instead of 0V. As a result, M_{N1} also helps charging node n1 toward V_{dd} – V_{TN}. The rise in node n1 is coupled to node n2 — the gate of M_{N3} has a transient pulse with its peak greater than V_{dd} . Therefore, node n1 also has a transient pulse with its peak exceeding $V_{dd} - V_{1N}$. Then, M_{P2} turns off and M_{N4} turns on n1 is pulled up to V_{dd} of 1V to conclude the write-logic-1 operation.

Logic-1 \rightarrow Logic-1 Write

In this case, before the single-bit-line write-logic-1 operation is executed, M_{N3} is off and both WBL and node n1 are at 1V. When WWL switches from low to high, M_{N1} will not turn on because its V_{GS} is equal to 0. At this time, since both M_{N1} and M_{N3} are off, node n1 maintains its logic-1 potential stably throughout the whole write-logic-1 cycle.

Logic-1 \rightarrow Logic-0 Write

In this case, before the single-bit-line write-logic-0 operation is executed, node n1 is at logic-1 (1V) since M_{N3} is off. Write bit line WBL is at logic-0 (0V). During the ramp-up of WWL above V_{TN} , M_{N1} turns on, thus node n1 is pulled down by the logic-0 of WBL. As a result, M_{N4} turns off and M_{P2} turns on, which leads to the turn-off of $M_{\rm Pl}$ and the turn-on of M_{N3} . At this time, node n1 is charged by M_{N3} and discharged by M_{NI}. As a result, node n1 slews upward to a potential about 0.15V, which is determined by the ratioedlogic structure of M_{N1} and M_{N3} as described in the logic-0 \rightarrow logic-0 case. When the write-logic-0 access is over, WWL ramps down. As in the logic-0 \rightarrow logic-0 case, during the initial ramp-down of WWL, the transconductance of M_{NI} becomes smaller. As a result, despite the down-slew of WWL, due to the ratioed-logic structure of M_{N1} and M_{N3} , the voltage of node n1 slews upward during the initial rampdown of WWL. When WWL is below $V_{\text{\tiny TN}},\,M_{N1}$ turns off, and the voltage of node n1 slews downward with the rampdown of WWL. When WWL comes down to the logic-0 level (0V), node n1 is also pulled down to 0V. This accomplishes the logic-1 \rightarrow logic-0 write operation.

As shown in Fig. 4, among four write cases, during the write pulse when WWL is high, in both logic- $0 \rightarrow$ logic-0 and logic- $1 \rightarrow$ logic-0 cases, node n1 is not at 0V. Instead, node n1 is at 0.15V. This may consume transient power consumption, but can be overcome by shortening the pulse width of WWL.



Figure 5. Layout of the SBLSRWA 6T SRAM cell.

The SBLSRWA SRAM cell consists of six transistors and two bit lines. In contrast, in the conventional two-port 8T SRAM cell, eight transistors and four bit lines are required. Thus, the SBLSRWA SRAM cell is much more compact as compared with the conventional two-port 8T SRAM cell. Something worth mentioning is that due to its asymmetrical configuration, the layout style of SBLSRWA 6T SRAM cell has to be different from that of the conventional 6T SRAM cell in order to minimize its area. In the conventional 6T SRAM cell (Fig. 1), the sources of NMOS devices M_{N3} and $M_{\rm N4}$ are both connected to ground, therefore they can share their layout regions to decrease the cell area. However, this technique cannot be applied to the SBLSRWA because the sources of M_{N3} and M_{N4} in it are no longer connected together. However, by sharing the source of M_{N3} with that of the cell at the left and the source of M_{N4} with that of the cell at the right, the layout area of the SBLSRWA 6T cell is almost the same as a conventional 6T SRAM cell. Fig. 5 shows the layout of the SBLSRWA 6T SRAM cell. Using a 0.25 μ m CMOS technology, its area is about 12μ m² and is much smaller than a conventional 8T two-port SRAM cell whose area is approximately $20\mu m^2$ — a more than 40% reduction in the layout area of an SRAM cell.

Conclusion

In this paper, a two-port 6T CMOS SRAM cell structure for low-voltage VLSI SRAM with single-bit-line simultaneous read-and-write access (SBLSRWA) capability has been described. With a unique structure of connecting the source terminal of an NMOS device in the SRAM cell to the write word line, this SRAM cell can be used to provide SBLSRWA capability for 1V two-port VLSI SRAM.

References

- T. S. Yang, M. A. Horowitz, and B. A. Wooley, "A 4ns 4Kx1 bit Two-Port BiCMOS SRAM," *IEEE Journal of Solid-State Circuits*, Vol. 23, Oct. 1988, pages 1030-1040.
- [2] M. Ukita, S. Murakami, T. Yamagata, H. Kuriyama, Y. Nishimura, and K. Anami, "A Single-Bit-Line Cross-Point Cell Activation (SCPA) Architecture for Ultra-Low-Power SRAM's," *IEEE Journal of Solid-State Circuits*, Vol. 28, No. 11, Nov. 1993, pages 1114-1118.
- [3] S. C. Liu and J. B. Kuo, "A Novel 0.7V Two-Port 6T SRAM Cell Structure with Single-Bit-Line Simultaneous Read-and-Write Access (SBLSRWA) Capability using PD SOI DTMOS Techniques," *IEEE* SOI Conference Dig., Sonoma County, CA, Oct 1999.